

◆ DESCRIPTION

The MT7406 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching, and low in-line power loss are needed in a very small outline surface mount package.

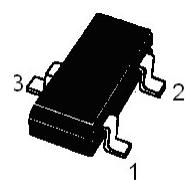
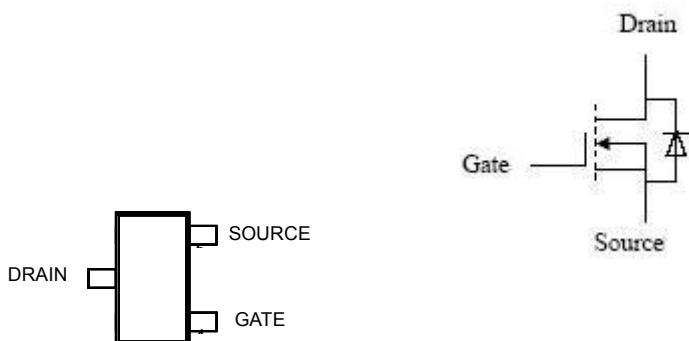
◆ FEATURES

- 20V/1.8A,R_{DS(ON)}=60mΩ@V_{GS}=4.5V
- 20V/1.5A,R_{DS(ON)}=85mΩ@V_{GS}=2.5V
- 20V/1.2A,R_{DS(ON)}=140mΩ@V_{GS}=1.8V
- Super high density cell design for extremely low R_{DS} (ON)
- Exceptional on-resistance and maximum DC current capability
- SOT-323 (SC-70-3L) package design

◆ APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

◆ PIN CONFIGURATION



N- Channel Enhancement Mode MOSFET

◆ **ABSOLUTE MAXIMUM RATINGS** ($T_A=25^\circ\text{C}$ Unless otherwise noted)

Parameter		Symbol	Maximum	Unit
Drain-Source Voltage		V_{DS}	20	V
Gate-Source Voltage		V_{GS}	± 12	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	1.8	A
	$T_C = 100^\circ\text{C}$		1.4	
Pulsed Drain Current		I_{DM}	10	A
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	0.35	W
	$T_C = 70^\circ\text{C}$		0.22	
Operating junction temperature range		T_J	-55 to 150	$^\circ\text{C}$
Storage temperature range		T_{STG}	- 55 to 150	$^\circ\text{C}$

◆ **THERMAL RESISTANCE RATINGS**

Thermal Resistance	Symbol	Maximum	Unit
Junction-to-Ambient	$R_{\theta JA}$	360	$^\circ\text{C}/\text{W}$

◆ **ORDERING INFORMATION**

Device	Package	Shipping
MT7406	SOT-323	3000 PCS / Tape & Reel

◆ **ELECTRICAL CHARACTERISTICS** ($T_A=25^\circ\text{C}$ Unless otherwise noted)

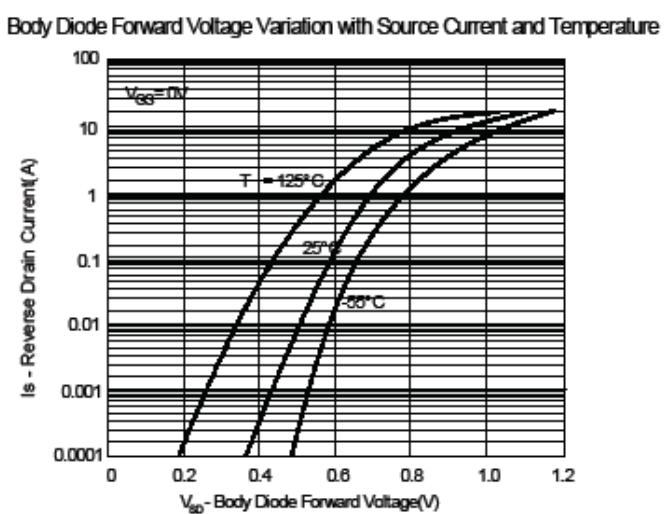
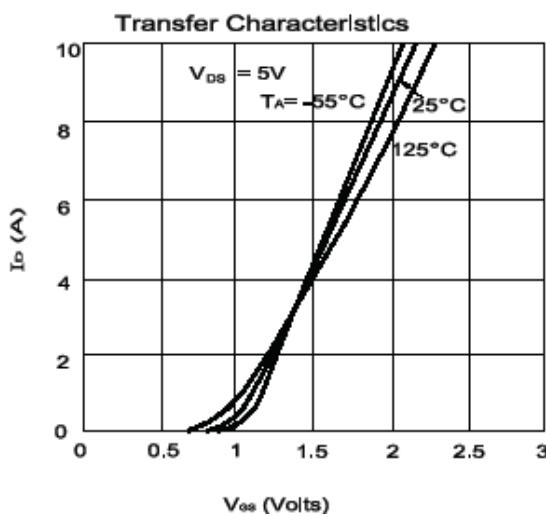
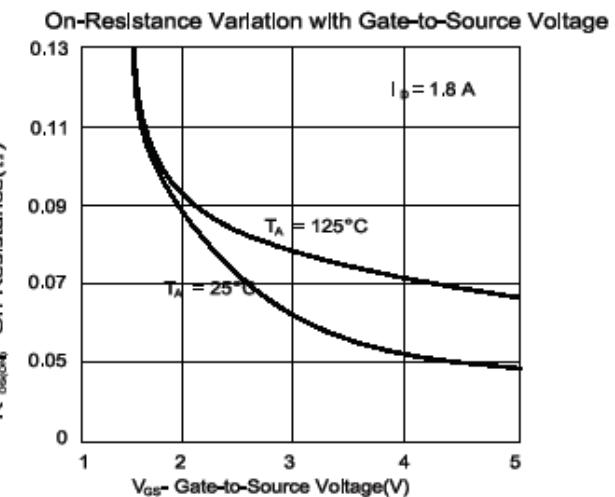
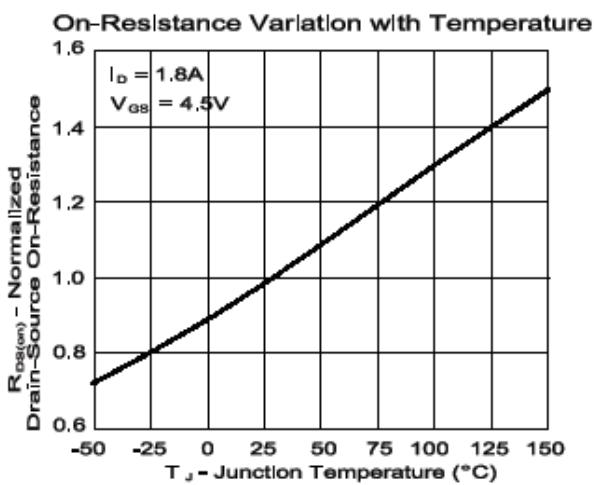
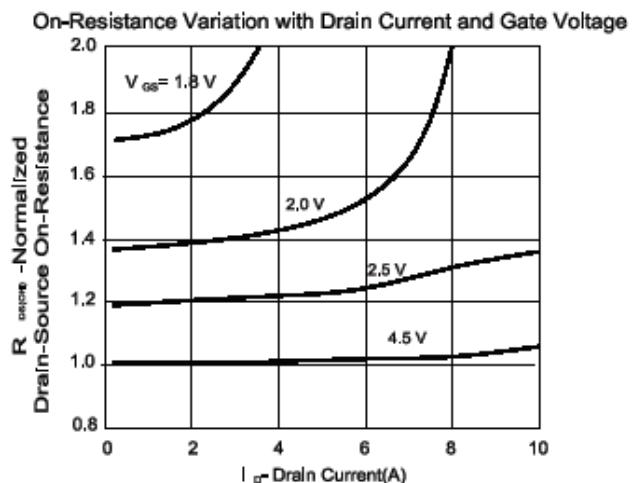
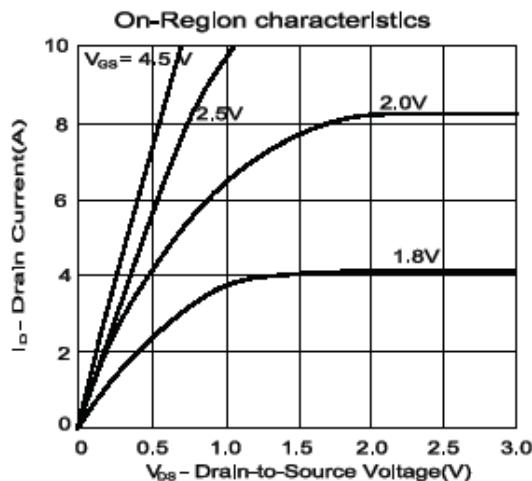
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_{\text{D}}=250\mu\text{A}$	20	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.4	0.8	1.2	V
Gate Leakage current	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 12\text{ V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 16\text{V}, V_{\text{GS}} = 0\text{ V}$	-	-	1	μA
		$V_{\text{DS}} = 16\text{V}, V_{\text{GS}} = 0\text{ V}, T_J=125^\circ\text{C}$	-	-	10	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}}=5\text{V}, V_{\text{GS}}=4.5\text{V}$	10	-	-	A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_{\text{D}}=1.8\text{A}$	-	50	60	$\text{m}\Omega$
		$V_{\text{GS}} = 2.5\text{V}, I_{\text{D}}=1.5\text{A}$	-	60	85	
		$V_{\text{GS}} = 1.8\text{V}, I_{\text{D}}=1.2\text{A}$	-	82	140	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=-1.8\text{A}$	-	5.5	-	S
Dynamic Parameters						
Input Cap.	C_{ISS}	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}$ $F=1\text{MHz}$	-	418	-	pF
Output Cap.	C_{OSS}		-	60	-	
Reverse Transfer Cap.	C_{RSS}		-	42	-	
Total Gate Charge ²	Q_g	$V_{\text{DS}}=0.5V_{(\text{BR})\text{DSS}}, V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=1.8\text{A}$	-	5.4	-	nC
Gate-Source Charge ²	Q_{gs}		-	0.7	-	
Gate-Drain Charge ²	Q_{gd}		-	1.7	-	
Turn-On Delay Time ²	$t_{\text{d}(\text{on})}$	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=1.0\text{A}, V_{\text{GS}}=4.5\text{V}, R_{\text{GS}}=2.5\Omega$	-	2.7	-	ns
Rise Time ²	t_r		-	2.5	-	
Turn-Off Delay Time ²	$T_{\text{d}(\text{off})}$		-	24	-	
Fall Time ²	t_f		-	3.2	-	
Source-Drain Diode Ratings and characteristics						
Continuous Current	I_s		-	-	0.9	V
Pulsed Current ³	I_{SM}		-	-	1.8	V
Diode Forward Voltage ¹	V_{SD}	$I_s = I_F, V_{\text{GS}}=0\text{V}$	-	-	1.0	V

Note :

1. Pulse test: PW<=300us duty cycle <=2%.
2. Independent of operating temperature.
3. Pulse width limited by maximum junction temperature.

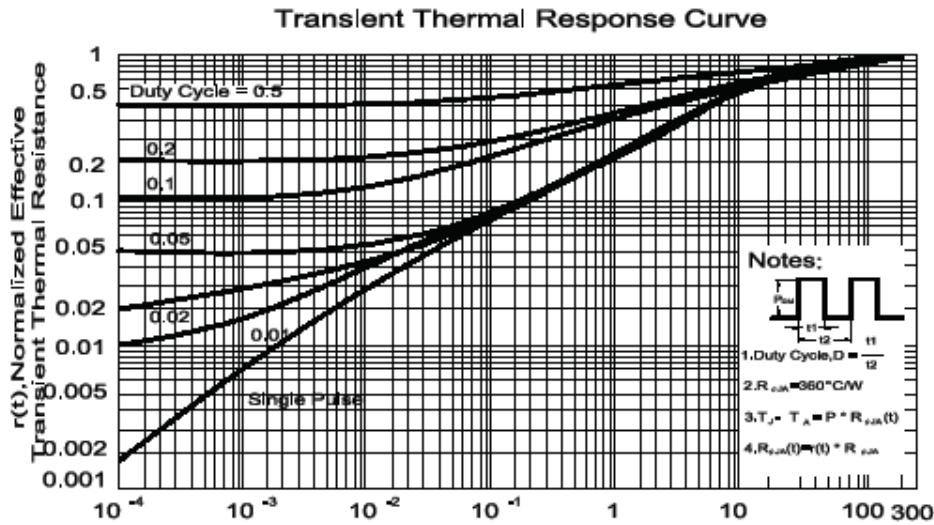
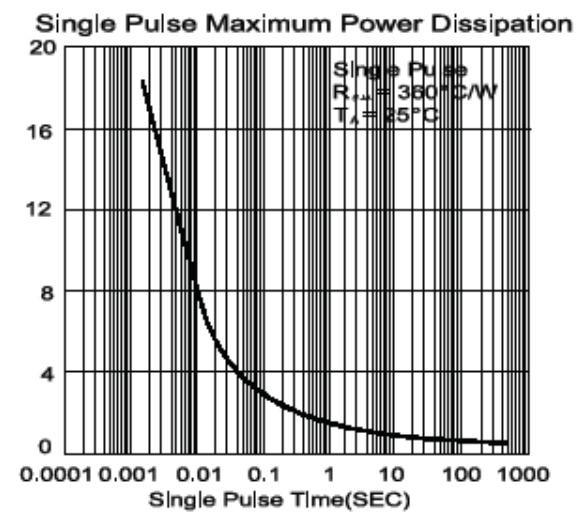
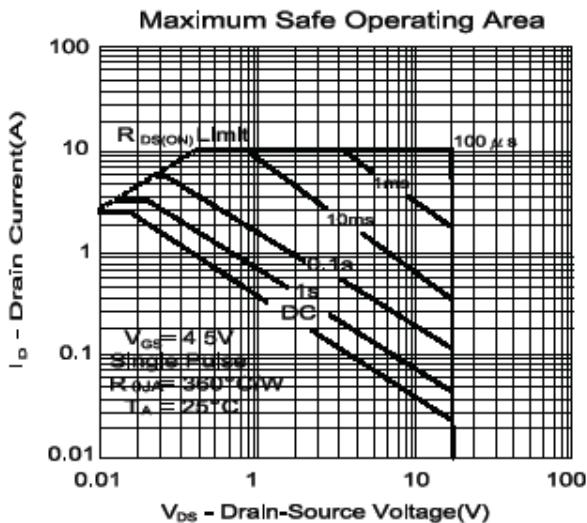
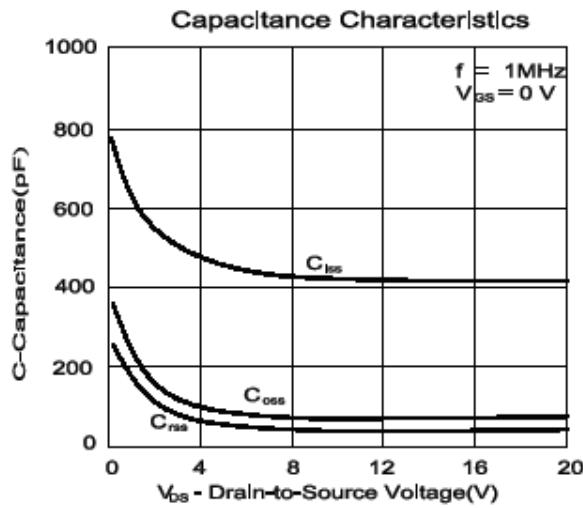
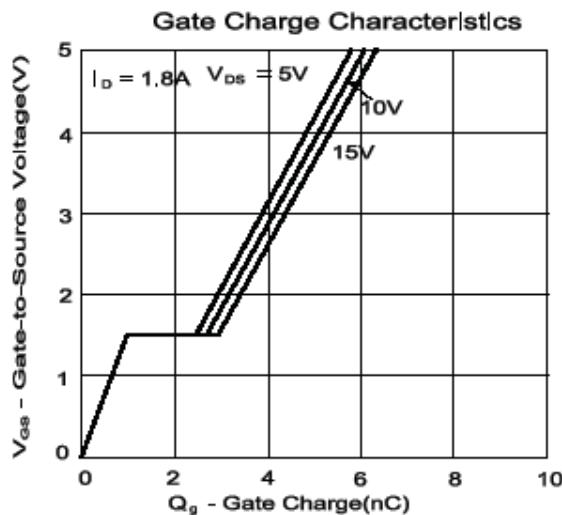


◆ TYPICAL CHARACTERISTICS





◆ TYPICAL CHARACTERISTICS



◆ PHYSICAL DIMENSIONS

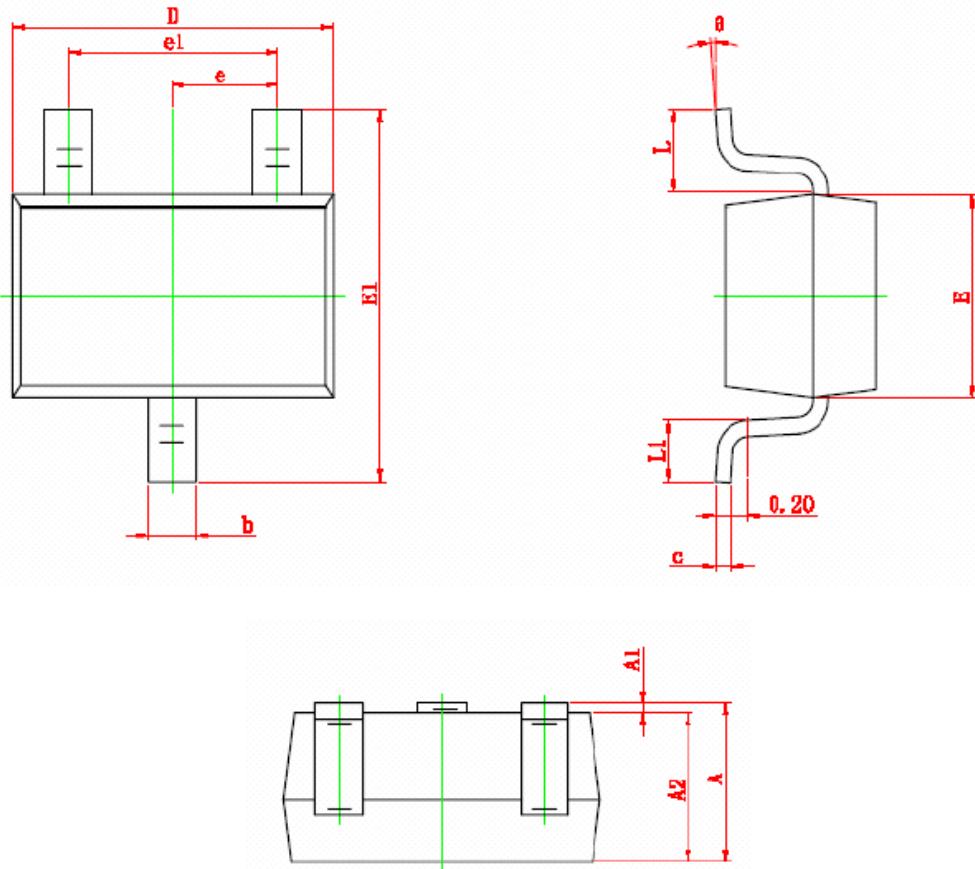


MATRIX MICROTECH CORP.

MT7406

N- Channel Enhancement Mode MOSFET

3-Pin surface Mount SOT-323



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°